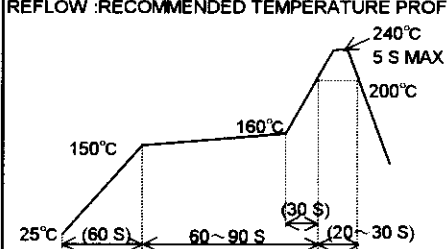


COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
△					△				
△					△				

APPLICATION STANDARD				
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C	STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C
	VOLTAGE	AC 50 V	OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY : 95 % MAX (NO DEW CONDENSATION IS PERMITTED)
	CURRENT	0.3 A		

SPECIFICATIONS					
ITEM	TEST METHOD	REQUIREMENT	QT	AT	
CONSTRUCTION					
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING	X	X	
MARKING	CONFIRMED VISUALLY.		X	X	
ELECTRICAL CHARACTERISTICS					
CONTACT RESISTANCE	100 mA (DC OR 1000 Hz).	70 mΩ MAX.	X	X	
INSULATION RESISTANCE	100 V DC.	100 MΩ MIN.	X	—	
VOLTAGE PROOF	150 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	X	X	
MECHANICAL CHARACTERISTICS					
INSERTION AND WITHDRAWAL FORCES	MEASURED BY APPLICABLE CONNECTOR.	INSERTION FORCE: 48 N MAX. WITHDRAWAL FORCE: 2 N MIN.	X	—	
MECHANICAL OPERATION	50 TIMES INSERTION AND EXTRACTIONS.	1)CONTACT RESISTANCE: 80 mΩ MAX. 2) NO DAMAGE, CRACK AND LOOSENESS OF PART.	X	—	
VIBRATION	FREQUENCY: 10 TO 55 Hz, SINGLE AMPLITUDE: 0.75 mm, — m/s ² AT 10 CYCLES FOR 3 DIRECTIONS.	1)NO ELECTRICAL DISCONTINUITY OF 1 μs MIN. 2)NO DAMAGE, CRACK AND LOOSENESS OF PART.	X	—	
SHOCK	490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.		X	—	
ENVIRONMENTAL CHARACTERISTICS					
DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C, 90~95 %, 96 h.	1)CONTACT RESISTANCE: 80 mΩ MAX. 2)INSULATION RESISTANCE: 100 MΩ MIN.	X	—	
RAPID CHAGE OF TEMPERTURE	TEMPERTURE -55→-15~35→ 85→15~35°C TIME 30→ 2~ 3→ 30→ 2~ 3 min. UNDER 5 CYCLES.	3)NO DAMAGE, CRACK AND LOOSENESS OF PART.	X	—	
DRY HEAT	EXPOSED AT 85 °C, 96 h.	1)CONTACT RESISTANCE: 80 mΩ MAX.	X	—	
COLD	EXPOSED AT -55 °C, 96 h.	2)NO DAMAGE, CRACK AND LOOSENESS OF PART.			
CORROSION SALT MIST	EXPOSED IN 5 % SALT WATER SPRAY FOR 48 h.	NO HEAVY CORROSION.	X	—	
SULPHUR DIOXIDE	EXPOSED IN 10 PPM FOR 96 h. (TEST STANDARD:JIS C 0090)	1)CONTACT RESISTANCE: 80 mΩ MAX. 2)NO HEAVY CORROSION.	X	—	
RESISTANCE TO SOLDERING HEAT	REFLOW :RECOMMENDED TEMPERATURE PROFILE  TO BE TESTED UNDER THE ABOVE CONDITIONS.	NO MELTING OF RESIN WHICH AFFECTS THE PERFORMANCE OF COMPONENT.	X	—	
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 235 °C FOR IMMERSION DURATION, 2 s.	NO PINHOLE OR DEWETTING ON SOLDERED SURFACE.	X	—	
REMARKS	DRAWN <i>J. Matsukawa</i> 00.06.20	DESIGNED <i>J. Matsukawa</i> 00.06.20	CHECKED <i>H. Okawa</i> 00.06.21	APPROVED <i>J. Fujimura</i> 00.06.23	RELEASED
UNLESS OTERWISE SPECIFIED ,REFER TO JIS C 5402.					
NOTE QT: QUALIFICATION TEST AT: ASSURANCE TEST X: APPLICABLE TEST					
HS HIROSE ELECTRIC CO.,LTD.		SPECIFICATION SHEET		PART NO. FX11B - 80P - SV0.5 (21)	
CODE NO.(OLD) CL	DRAWING NO. ELC4 - 152631 - 01	CODE NO. CL 573 - 0658- 9 - 21	1 1		